

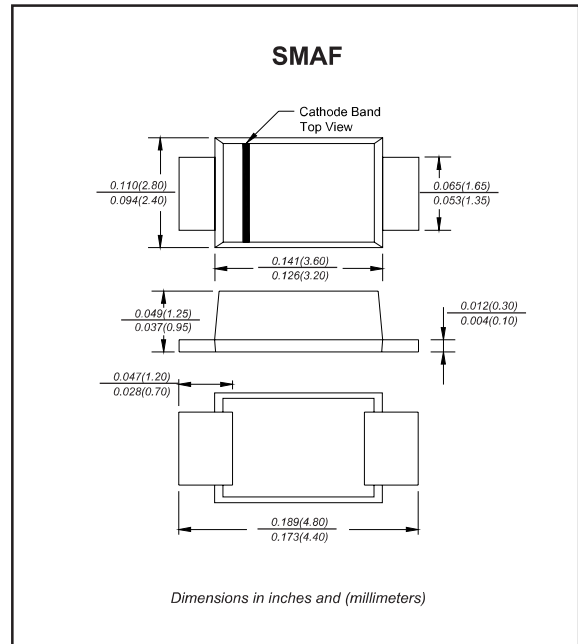
Features

- ▶ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ▶ For surface mounted applications
- ▶ Metal silicon junction, majority carrier conduction
- ▶ Low power loss, high efficiency
- ▶ Built-in strain relief, ideal for automated placement
- ▶ High forward surge current capability
- ▶ High temperature soldering guaranteed: 250°C/10 seconds at terminals
- ▶ Compliant to RoHS Directive 2011/65/EU
- ▶ Compliant to Halogen-free

Mechanical data

- ▶ **Case:** JEDEC SMAF molded plastic body
- ▶ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ▶ **Polarity:** Color band denotes cathode end
- ▶ **Mounting Position:** Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I_O			2.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			50	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	I_R			0.5	mA
	$V_R = V_{RRM} \quad T_A = 100^\circ\text{C}$				20	
Thermal resistance (1)	Junction to Ambient	$R_{\theta JA}$		78		$^\circ\text{C}/\text{W}$
	Junction to Case	$R_{\theta JC}$		18		
	Junction to Lead	$R_{\theta JL}$		20		
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		220		pF
Storage temperature		T_{STG}	-65		+150	$^\circ\text{C}$

Note: (1) Device mounted on p.c.b. with 10 mm x 20 mm x 0.1 mm copper pad area.

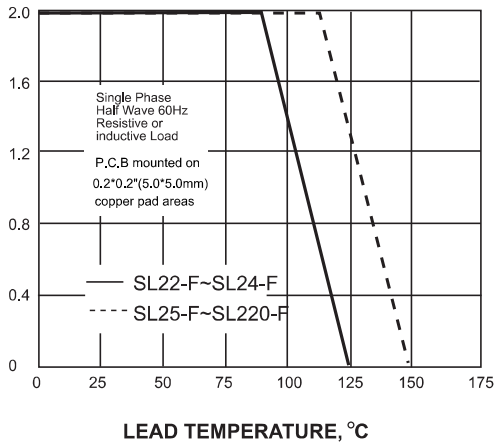
SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature T_J ($^\circ\text{C}$)
SL22-F	20	14	20	0.45	
SL23-F	30	21	30		
SL24-F	40	28	40		
SL25-F	50	35	50	0.55	-55 to +150
SL26-F	60	42	60		
SL28-F	80	56	80	0.75	
SL210-F	100	70	100		
SL215-F	150	105	150	0.85	
SL220-F	200	140	200		

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage@ $I_F=2.0\text{A}$

Rating and characteristic curves

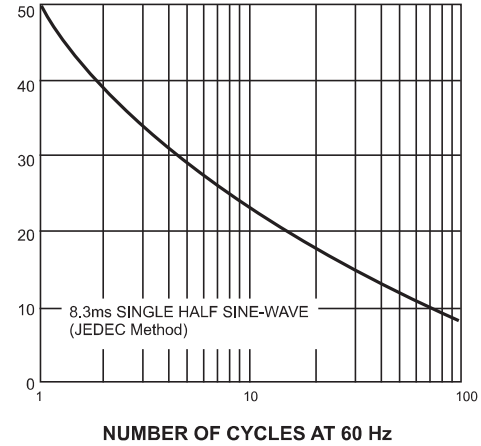
AVERAGE FORWARD RECTIFIED CURRENT, AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



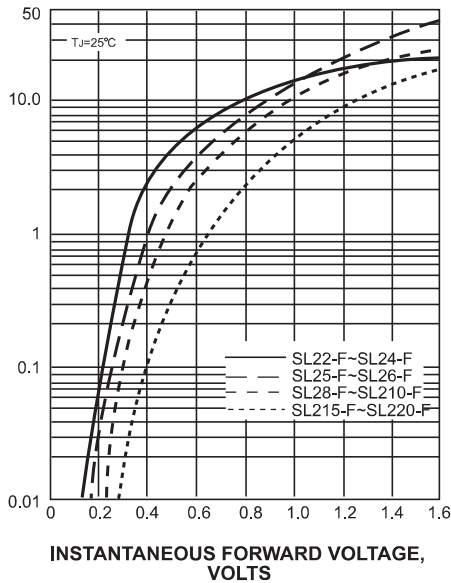
PEAK FORWARD SURGE CURRENT, AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



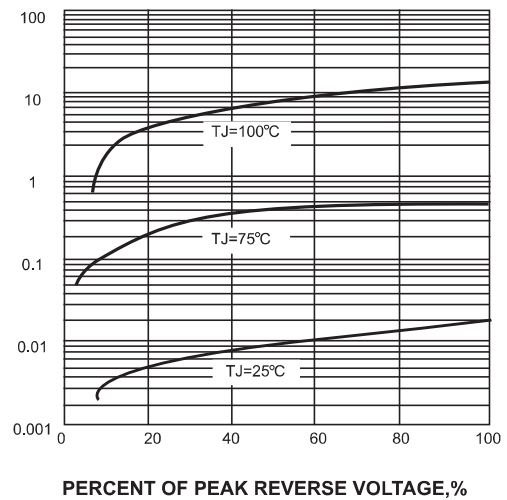
INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



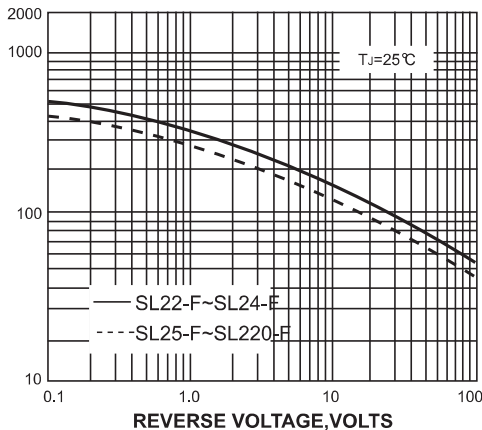
INSTANTANEOUS REVERSE CURRENT, MILLIAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



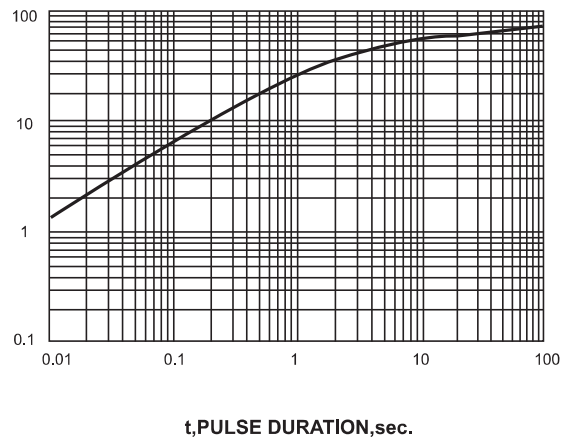
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE

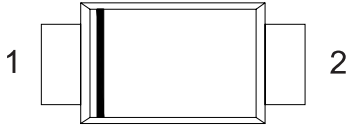



TRANSIENT THERMAL IMPEDANCE, °C/W

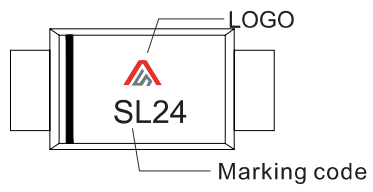
FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



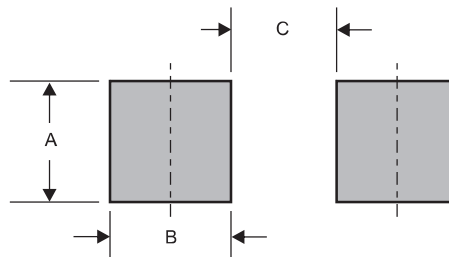
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code	Example
SL22-F	SL22	
SL23-F	SL23	
SL24-F	SL24	
SL25-F	SL25	
SL26-F	SL26	
SL28-F	SL28	
SL210-F	SL210	
SL215-F	SL215	
SL220-F	SL220	

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMAF	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)